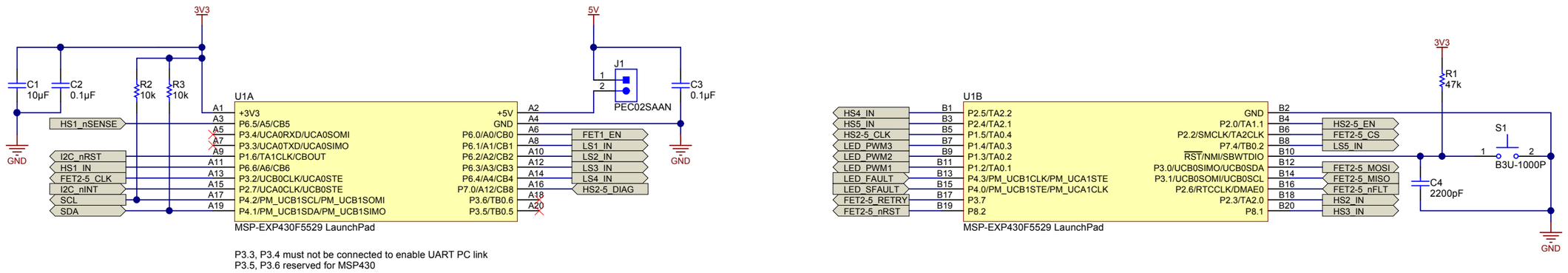
MSP430F55 LaunchPad Pinout



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Number: SAT0103	Rev: E1	Designed for: Public Release	Mod. Date: 7/07/2014
		Project Title: BCM Driver Reference Design	
		Sheet Title: MSP430 LaunchPad Pin Connections	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 2 of 12
Drawn By:		File: MSP430.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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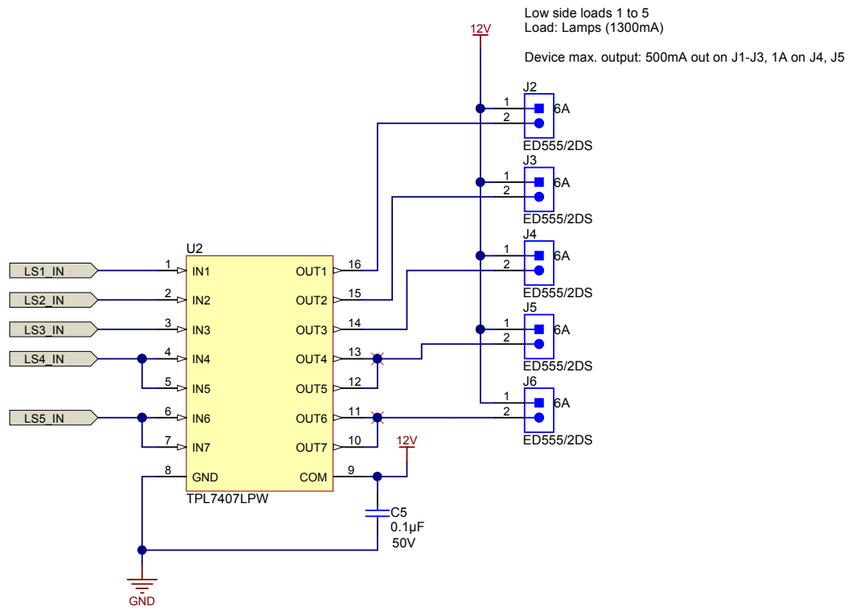
Low Side Driver

Channels: 1-5



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Number: SAT0103	Rev: E1	Designed for: Public Release	Mod. Date: 7/07/2014
		Project Title: BCM Driver Reference Design	
		Sheet Title: Low Side Driver: Ch 1-5	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 3 of 12
Drawn By:		File: TPL7407L.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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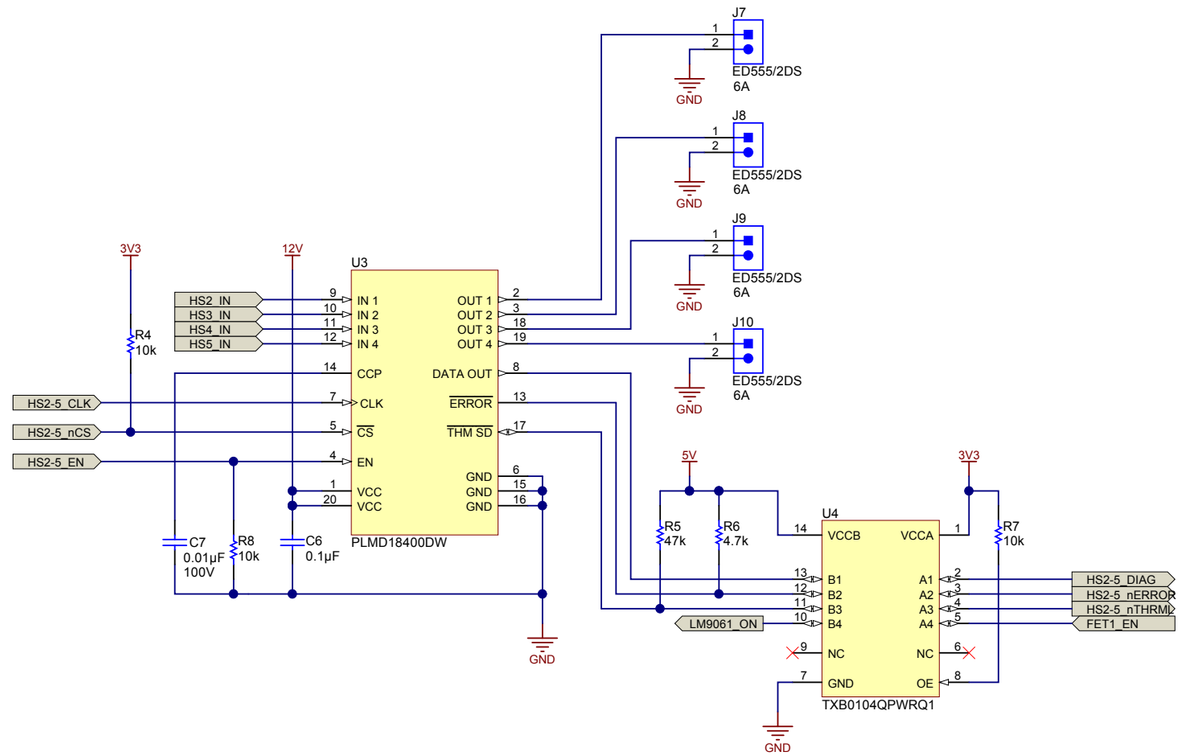
High Side Driver

Channels: 2-5

High side loads 2 to 5
Load: Window actuator + Windshield wiper actuator (4x 250mA relay)

Device max. output: 1A each channel, 3.75A max total



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Designed for: Public Release		Mod. Date: 11/07/2014	
Project Title: BCM Driver Reference Design			
Number: SAT0103	Rev: E1	Sheet Title: High Side Driver: Ch 2-5	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 4 of 12
Drawn By:		File: LMD18400.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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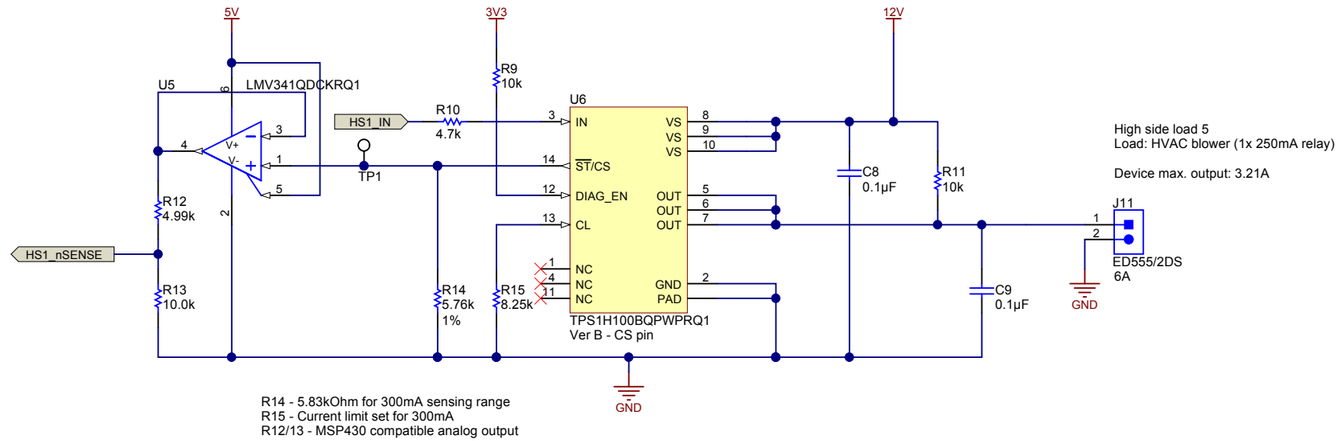
High Side Driver

Channel: 5



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Number: SAT0103	Rev: E1	Designed for: Public Release	Mod. Date: 11/07/2014
SVN Rev: Not in version control		Project Title: BCM Driver Reference Design	
Drawn By:		Sheet Title: High Side Driver: Ch 5	
Engineer: Derrick Kickel		Assembly Variant: [No Variations]	Sheet: 5 of 12
		File: TPS1H100B.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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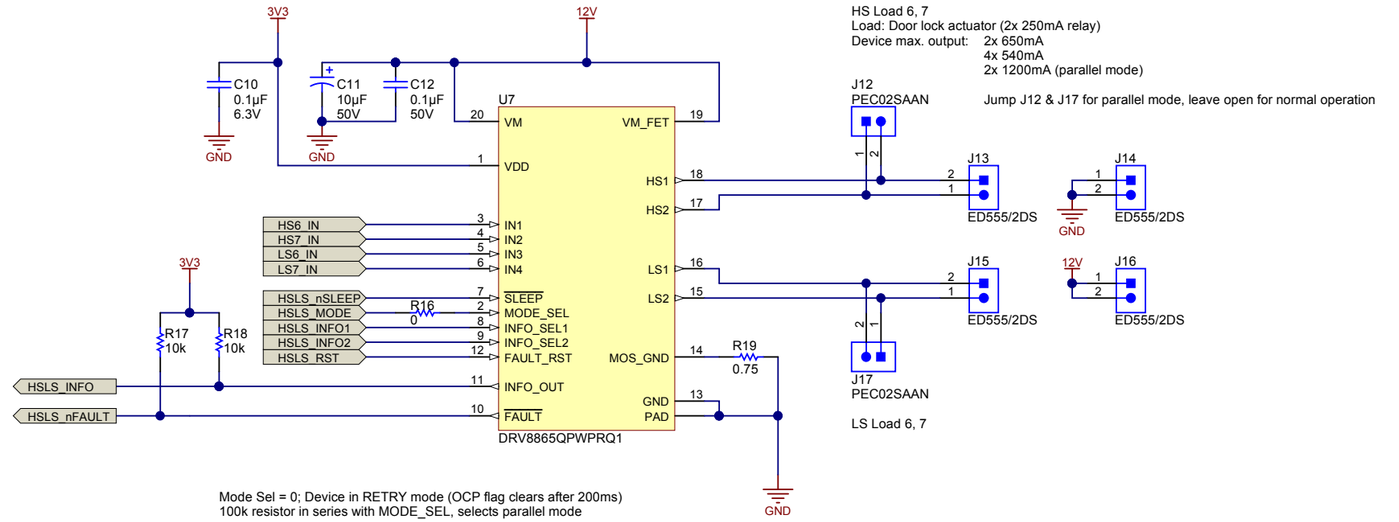
High Side/Low Side Driver

HS Channels: 6-7
LS Channels: 6-7



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Number: SAT0103	Rev: E1
SVN Rev: Not in version control	
Drawn By:	
Engineer: Derrick Kickel	

Designed for: Public Release	Mod. Date: 7/07/2014
Project Title: BCM Driver Reference Design	
Sheet Title: High Side/Low Side Driver: HS Ch 6-7, LS Ch 6-7	
Assembly Variant: [No Variations]	Sheet: 6 of 12
File: DRV8865.SchDoc	Size: B
Contact: http://www.ti.com/support	

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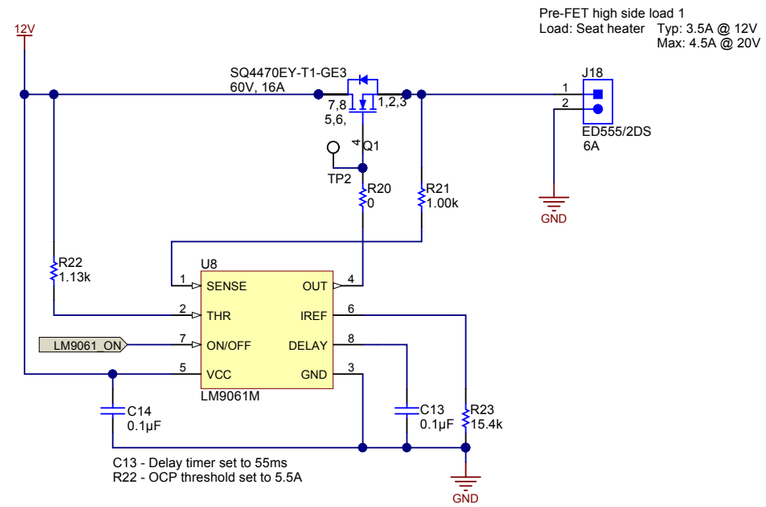
High Side Pre-FET Driver

Channel: 1



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		Designed for: Public Release	Mod. Date: 14/07/2014
		Project Title: BCM Driver Reference Design	
Number: SAT0103	Rev: E1	Sheet Title: High Side Pre-FET Driver: Ch 1	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 7 of 12
Drawn By:		File: LM9061.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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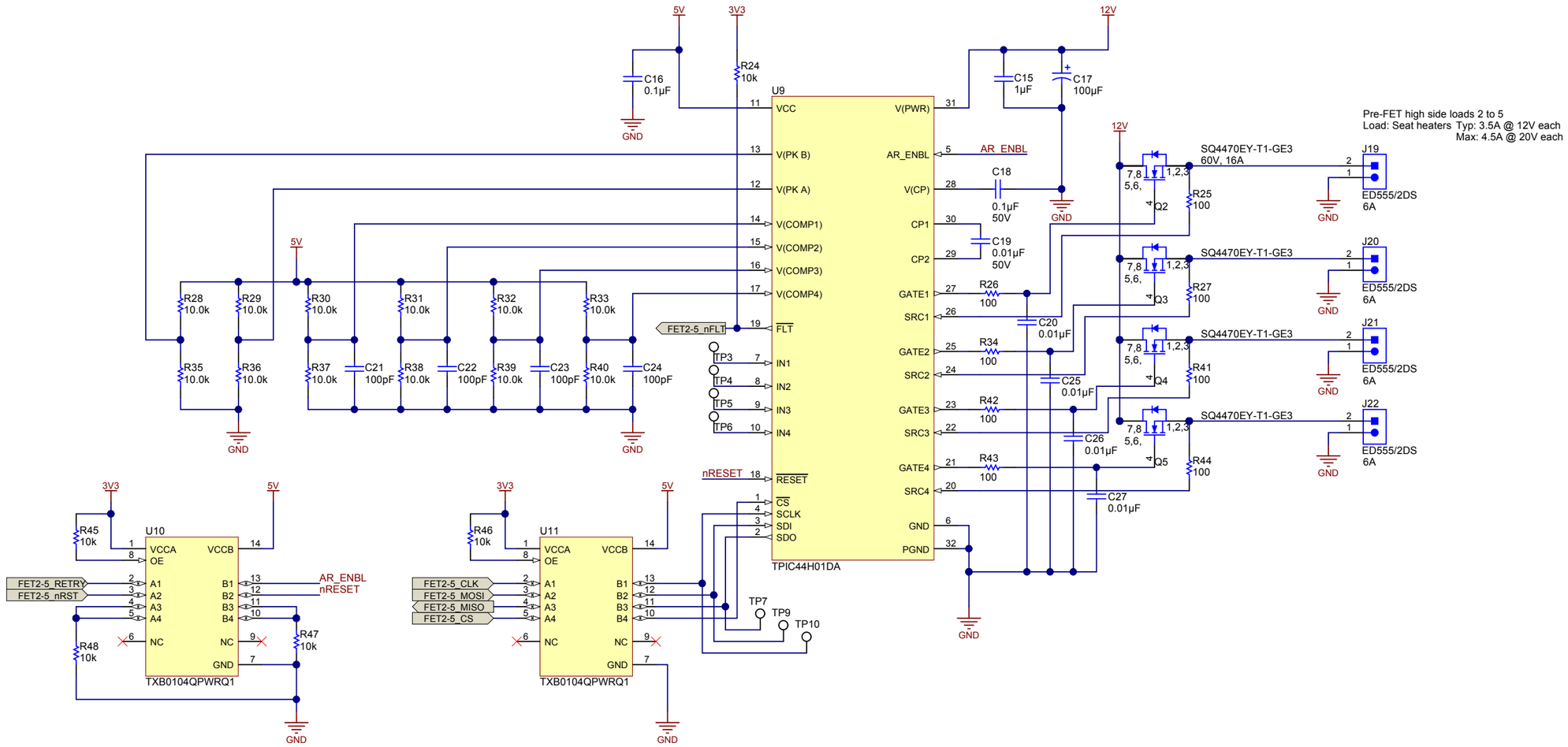
High Side Pre-FET Driver

Channels: 2-5



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Number: SAT0103	Rev: E1	Designed for: Public Release	Mod. Date: 4/08/2014
SVN Rev: Not in version control		Project Title: BCM Driver Reference Design	
Drawn By:		Sheet Title: High Side Pre-FET Driver: Ch 2-5	
Engineer: Derrick Kickel		Assembly Variant: [No Variations]	Sheet: 8 of 12
		File: TPIC44H01.SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com

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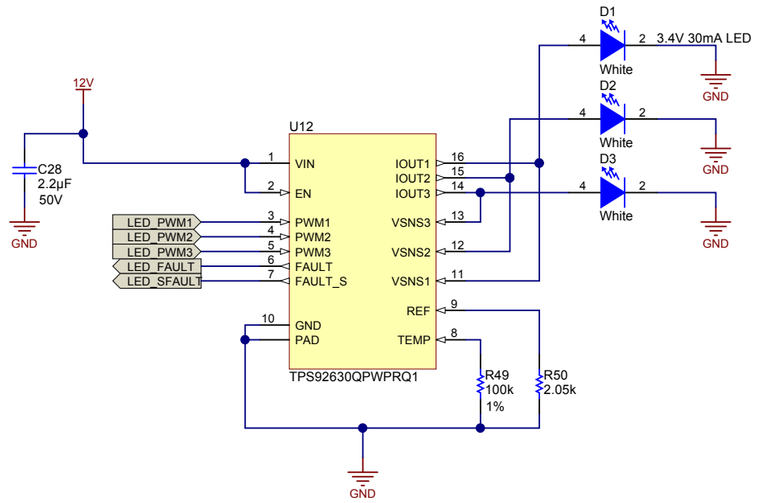
LED Driver

Channels: 1-3



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Designed for: Public Release		Mod. Date: 7/07/2014	
Project Title: BCM Driver Reference Design			
Number: SAT0103	Rev: E1	Sheet Title: LED Driver: Ch 1-3	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 9 of 12
Drawn By: Derrick Kickel		File: TPS92630.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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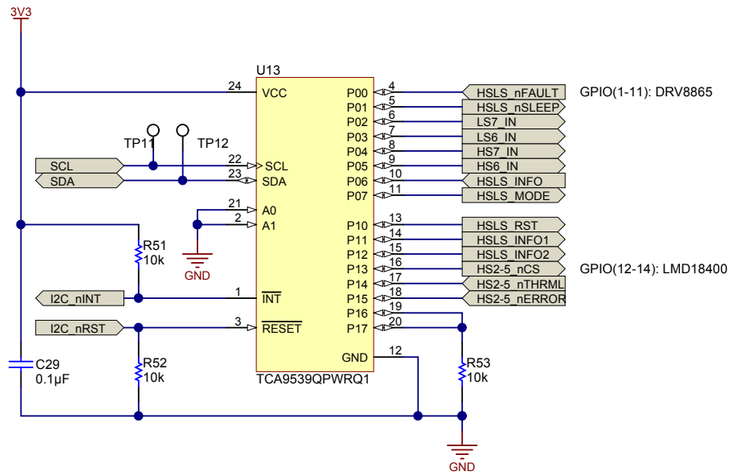
I2C GPIO Expansion



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Number: SAT0103	Rev: E1	Designed for: Public Release	Mod. Date: 7/07/2014
SVN Rev: Not in version control		Project Title: BCM Driver Reference Design	
Drawn By:		Sheet Title: I2C GPIO Expansion	
Engineer: Derrick Kickel		Assembly Variant: [No Variations]	Sheet: 10 of 12
		File: TCA9539.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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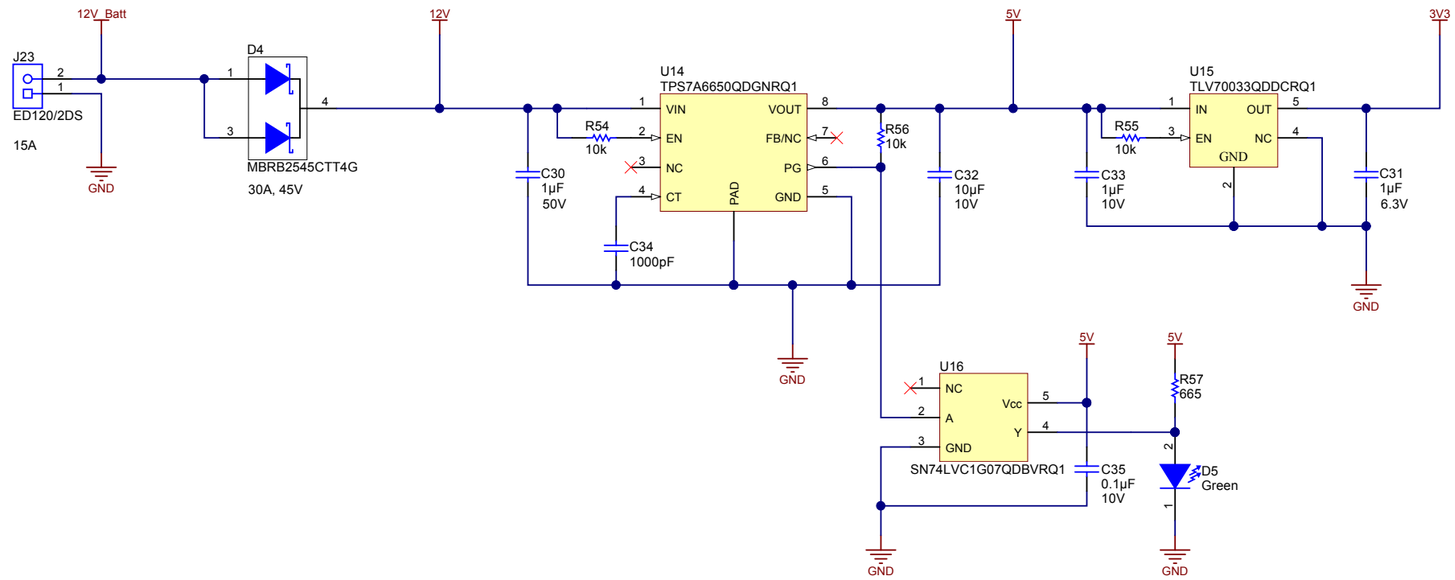
Power

Car Battery
12V typical
9-20V typical continuous range
40V load dump transients



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Designed for: Public Release		Mod. Date: 14/07/2014	
Project Title: BCM Driver Reference Design			
Number: SAT0103	Rev: E1	Sheet Title: Power	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 11 of 12
Drawn By:		File: Power.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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H1 NY PMS 440 0025 PH
H2 NY PMS 440 0025 PH
H3 NY PMS 440 0025 PH
H4 NY PMS 440 0025 PH

H5 1902C
H6 1902C
H7 1902C
H8 1902C

FID1 FID2 FID3

PCB Number: SAT0103
PCB Rev: E1

PCB
LOGO
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You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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		Designed for: Public Release	Mod. Date: 3/07/2014
		Project Title: BCM Driver Reference Design	
Number: SAT0103	Rev: E1	Sheet Title: Hardware	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 12 of 12
Drawn By:		File: Hardware.SchDoc	Size: B
Engineer: Derrick Kickel		Contact: http://www.ti.com/support	

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